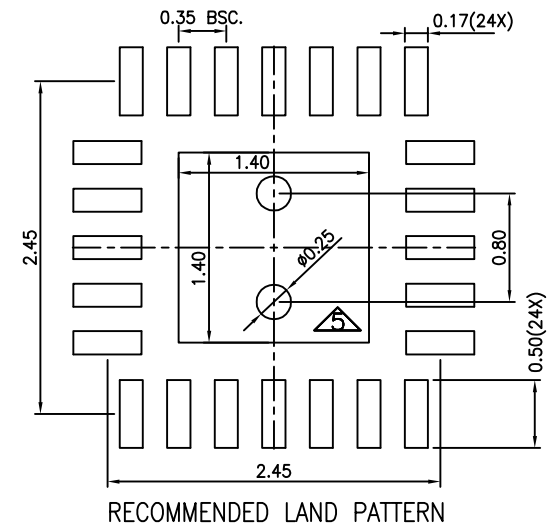
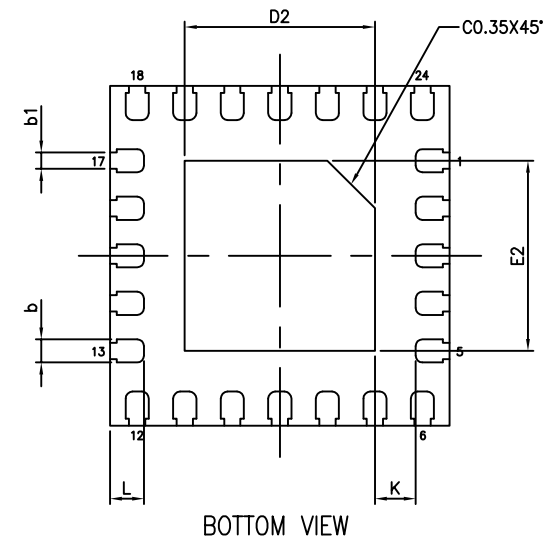
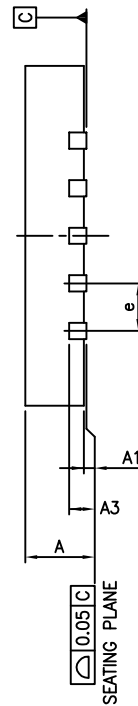


| SYMBOLS | MIN. | NOM. | MAX. |
|---------|------------|------|------|
| A | 0.40 | 0.45 | 0.50 |
| A1 | 0.00 | 0.02 | 0.05 |
| A3 | 0.127 REF. | | |
| b | 0.12 | 0.17 | 0.22 |
| b1 | 0.07 | 0.12 | 0.17 |
| D | 2.45 | 2.50 | 2.55 |
| E | 2.45 | 2.50 | 2.55 |
| e | 0.35 BSC | | |
| L | 0.20 | 0.25 | 0.30 |
| K | 0.20 | — | — |
| D2 | 1.35 | 1.40 | 1.45 |
| E2 | 1.35 | 1.40 | 1.45 |



NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-288
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA



PERICOM
A PRODUCT LINE
OF DIODES
INCORPORATED
ENABLING SERIAL CONNECTIVITY

DATE: 06/26/19

DESCRIPTION: 24-Contact, Extra Thin Fine Pitch QFN, X1QFN

PACKAGE CODE: XEB (XEB24)

DOCUMENT CONTROL #: PD-2243

REVISION: --